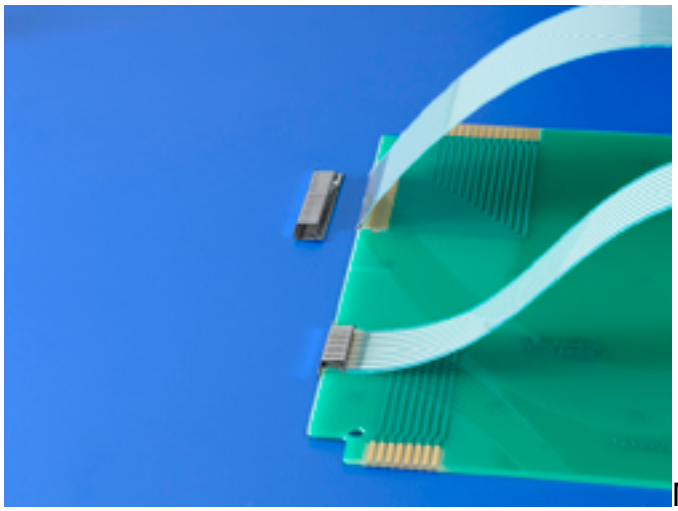
Molex ClipLok Interconnect Clip Firmly Secures Circuit-to-Board Connections



Molex recently released the ClipLok™ interconnect clip, an electomechanical connection that easily attaches to secure a membrane switch or FPC tail firmly to a printed circuit board, eliminating the need for mating connectors at each point. A first-to-market product, the low-profile ClipLok interconnect clip provides immediate and reliable circuit-to-board connectivity in a range of consumer, medical, networking and telecommunications applications.

“Today’s user interface technologies are more demanding and complex. Custom product designs including membrane switches, capacitive switches, touchscreens, display flex assemblies and flex circuit jumpers may all benefit from the ClipLok interconnect technology”

“Product integrity is tantamount to Molex customers. The low-profile ClipLok connector design delivers robust features: strong mechanical attachment, excellent electrical integrity, far lower product cost and ease of assembly,” notes Todd Hester, vice president and general manager of printed circuit products, Molex.

The latest addition to the Molex line of integrated switch assemblies, the ClipLok interconnect clip offers a less bulky alternative to other circuit-to-board interconnect methods. The mechanical component securely bonds circuits together by means of a spring-type mechanism. Electrical connections are achieved when the switch circuits are wrapped around the edge of the board. Finally, a built-in feature on each ClipLok interconnect clip guides the assembler in the correct placement of the clip and circuit.

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interconnect technology," adds Hester.

Molex's ClipLok interconnect clip and membrane switch assemblies are qualified through tests based on ASTM (American Society of Testing and Material) standards. All Molex manufacturing facilities are ISO9000 and ISO14000 certified. For additional information about ClipLok interconnect clip features and applications, please visit Molex. To receive information on other Molex products and industry solutions, please click here.

For more information please visit, www.molex.com [1]

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